

Title (en)  
MOLDED RESIN AND METHOD OF PRODUCTION THEREOF

Publication  
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Application  
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Abstract (en)  
[origin: WO9211122A1] A molded resin having a double structure in which the outside of a core layer resin consisting of a resin layer foamed to a void content of 30 SIMILAR 80 % is wrapped up in a skin layer resin; and a method of production of the molded resin which comprises injecting the skin layer resin and, then or at the same time, the core layer resin which is foamed inside a molding apparatus into a molding die.

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IPC 8 full level  
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**B29C 45/1604** (2013.01 - EP)

Citation (search report)  
• [X] US 4155969 A 19790522 - HENDRY JAMES W [US]  
• [Y] FR 2256021 A1 19750725 - ASAHI DOW LTD [JP]  
• [X] GB 2132932 A 19840718 - HOOVER UNIVERSAL  
• [X] US 4124308 A 19781107 - SOKOLOW NICKOLAS N  
• [X] MACHINE DESIGN vol. 44, no. 6, 29 June 1972, pages 68 - 71 OGORKIEWICZ R. M. 'SANDWICH MOLDING'  
• [A] PATENT ABSTRACTS OF JAPAN vol. 11, no. 102 (M-576)(2549) 31 March 1987 & JP-A-61 252 121 ( MEIKI CO. LTD. ) 10 November 1986  
• See references of WO 9211122A1

Cited by  
GB2463712A; DE19617349C1; US6702978B1; WO2005102667A3

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